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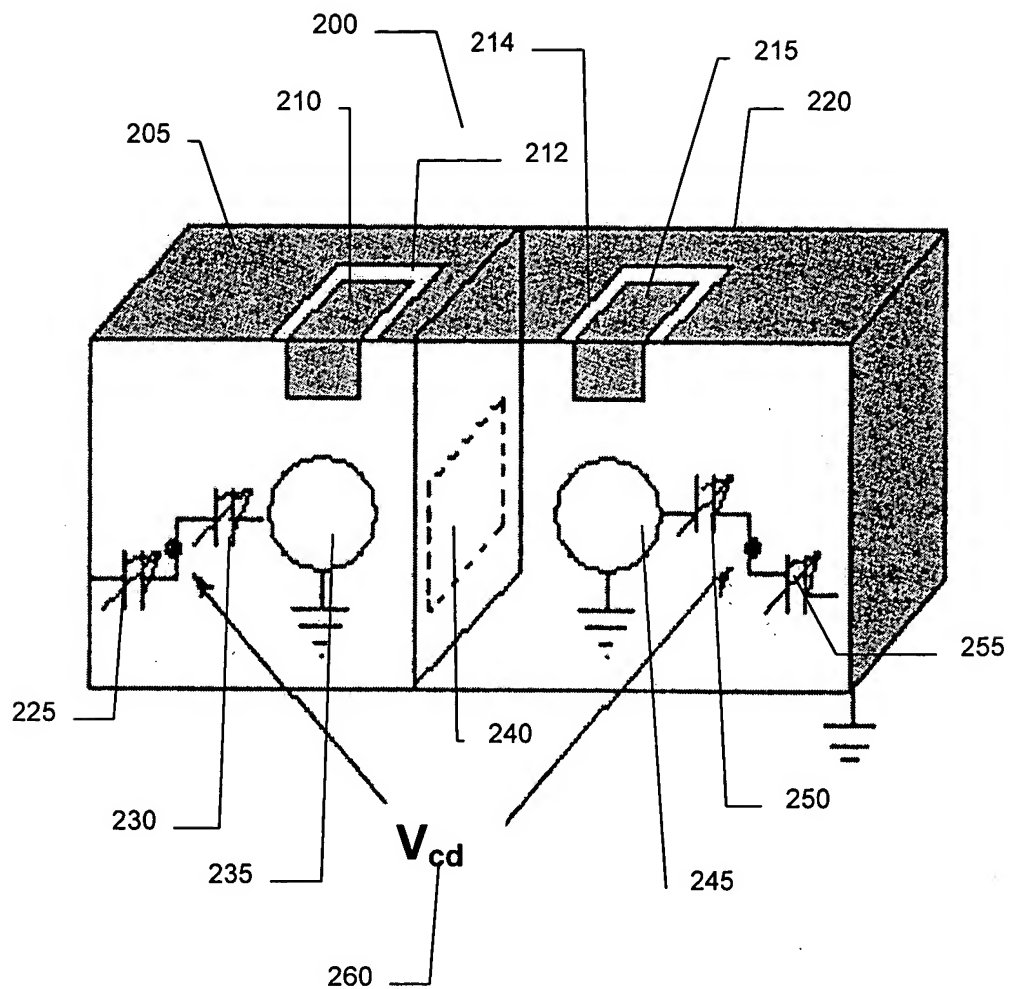


FIGURE 2

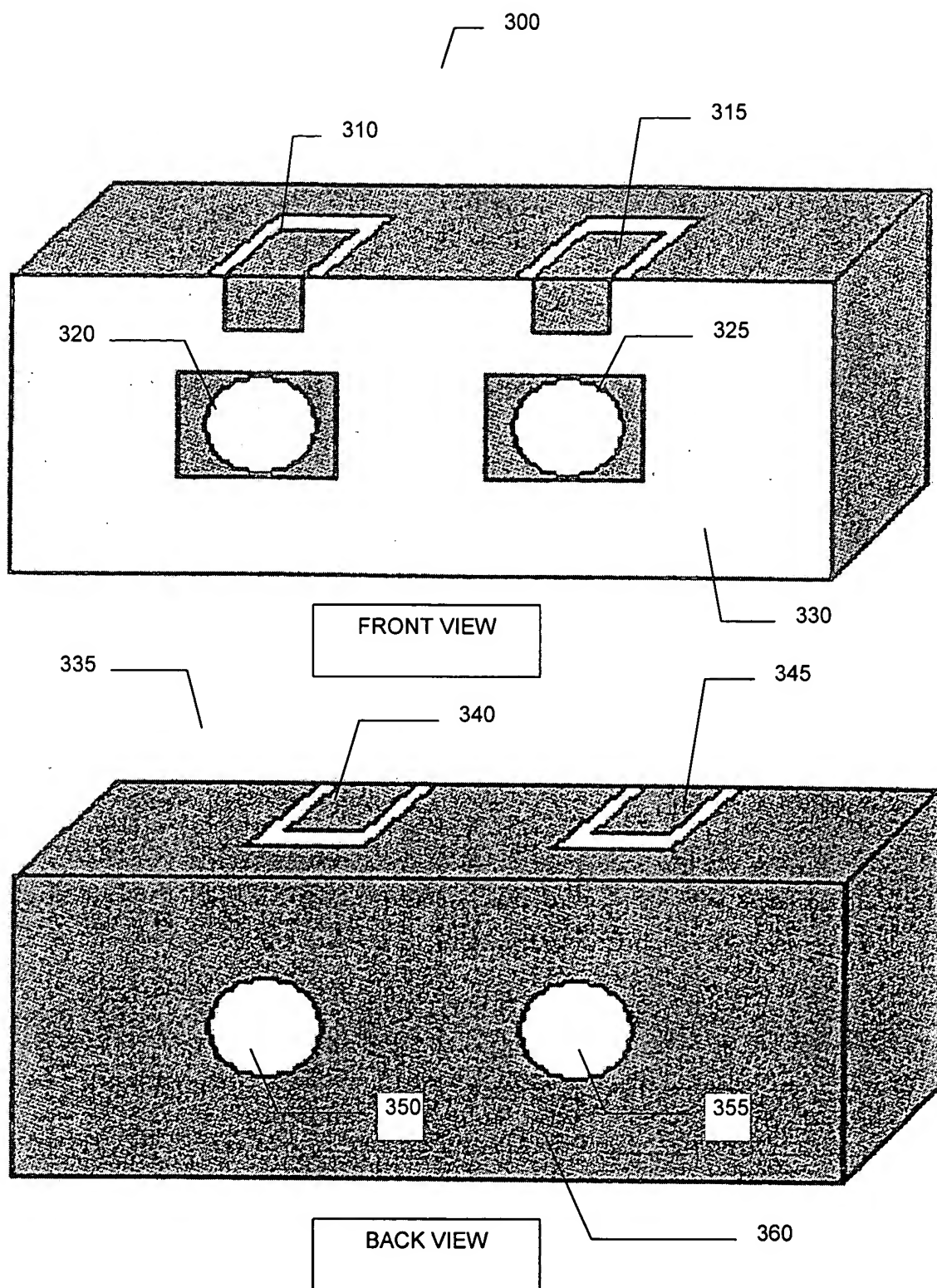


FIGURE 3

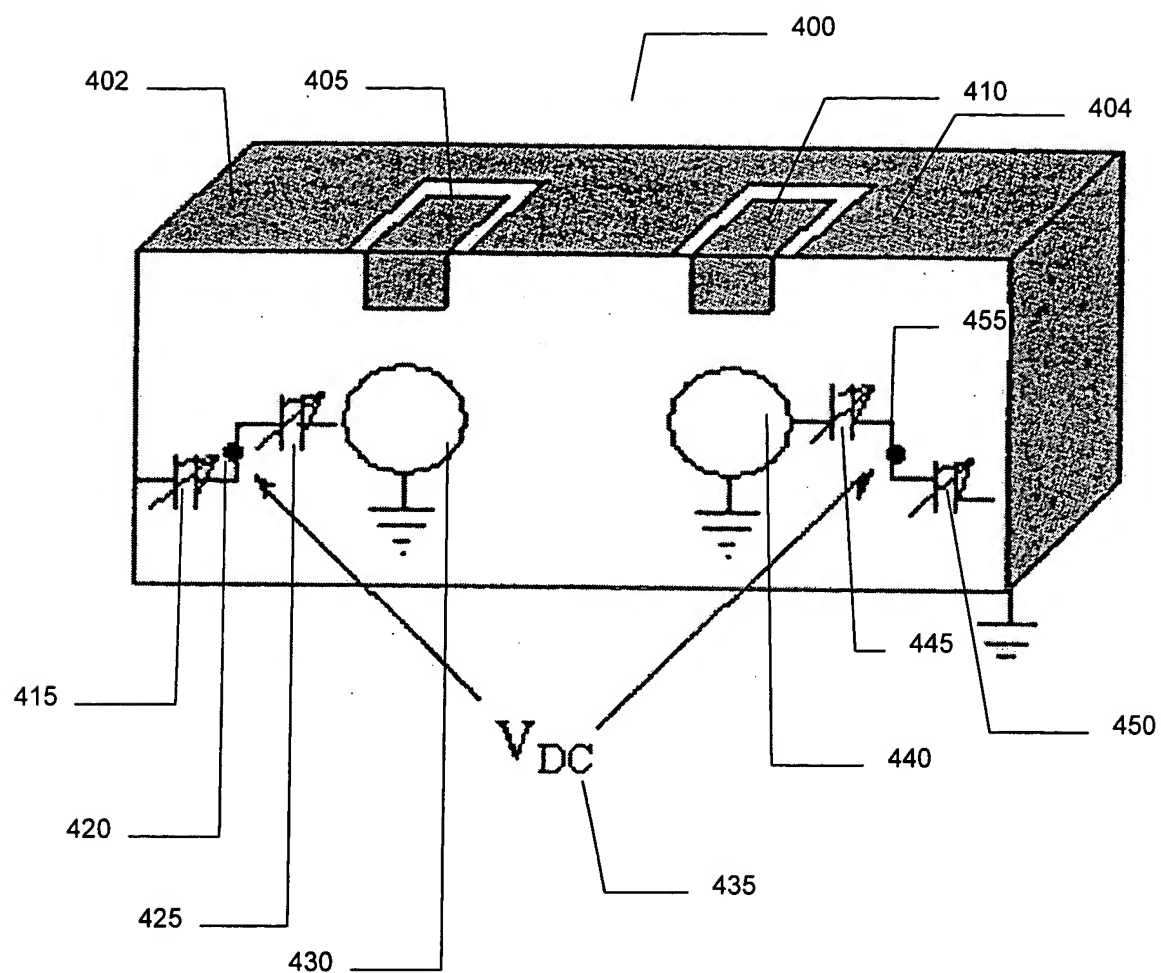


FIGURE 4



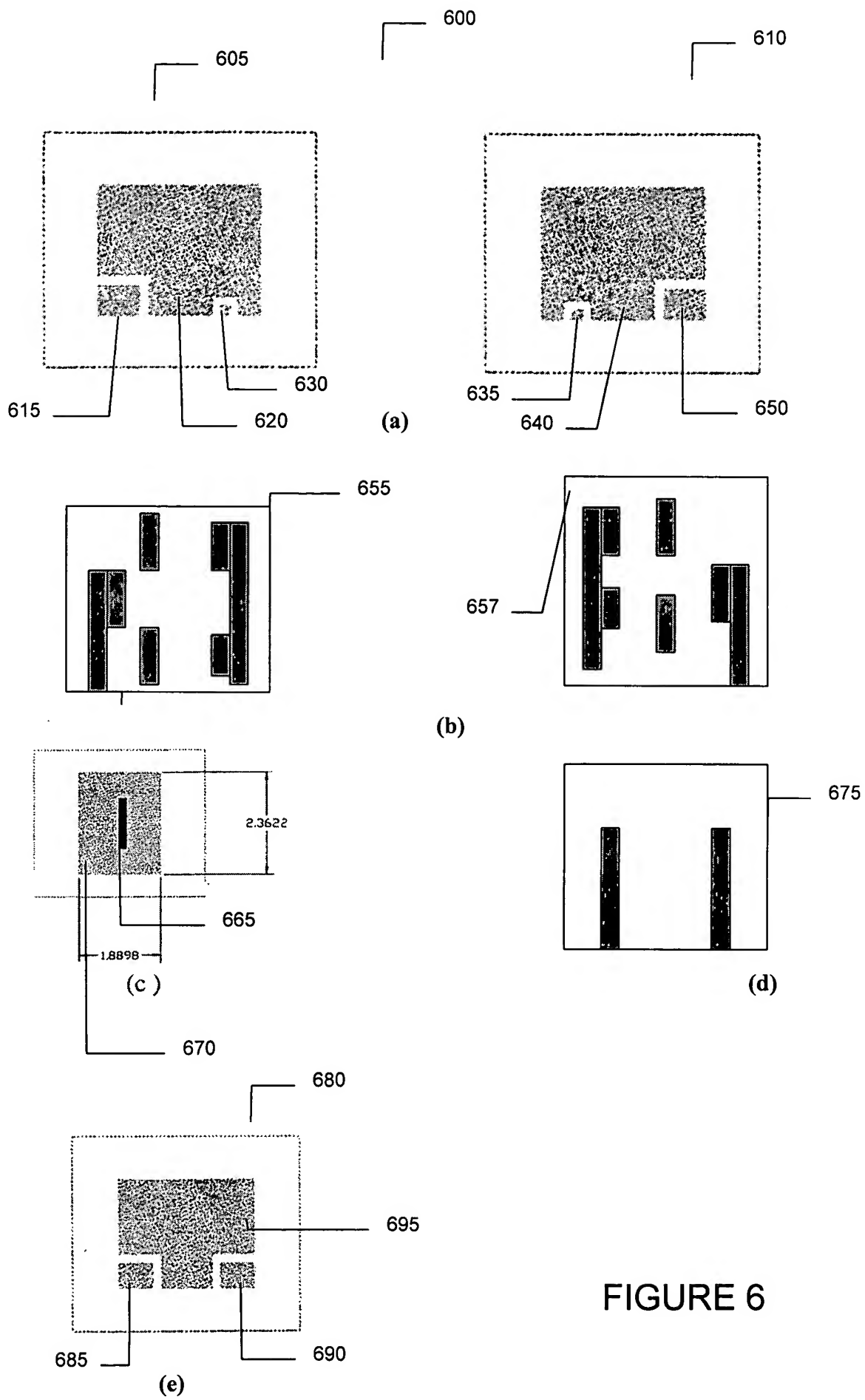


FIGURE 6

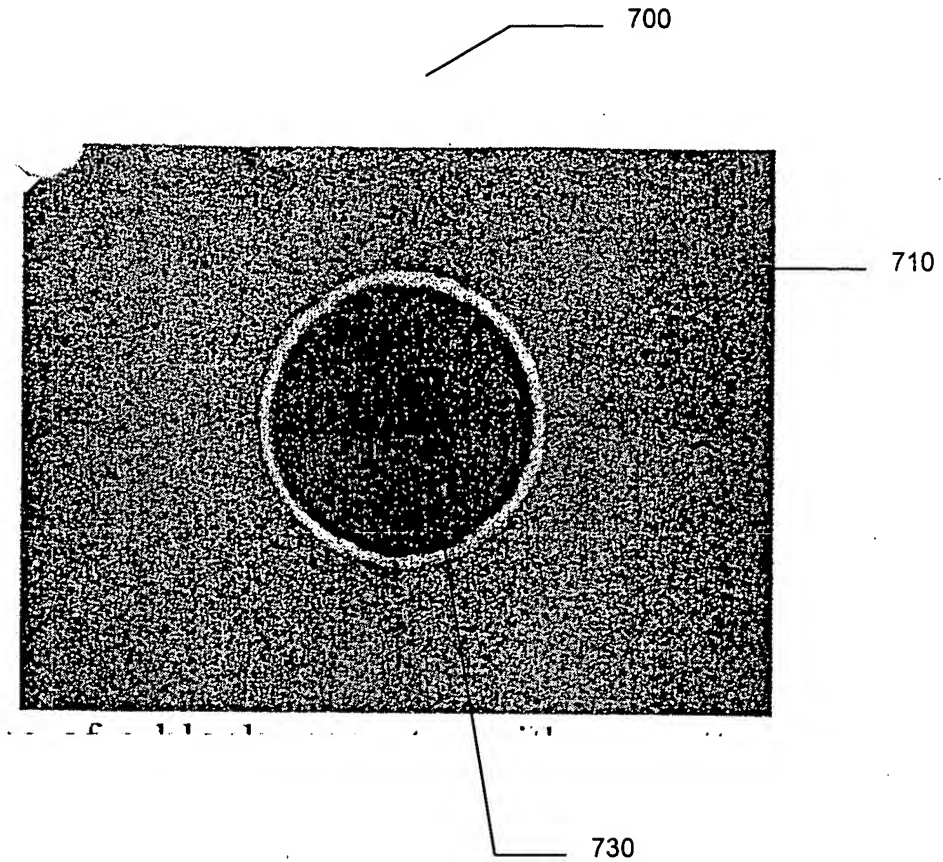


FIGURE 7

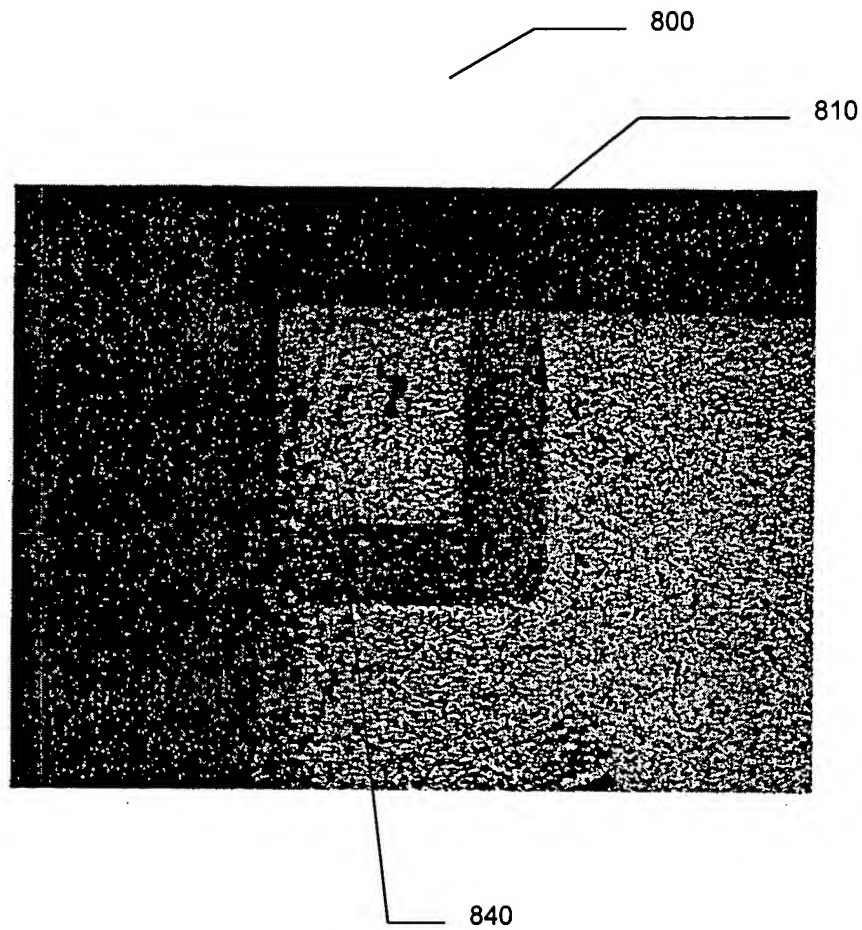


FIGURE 8

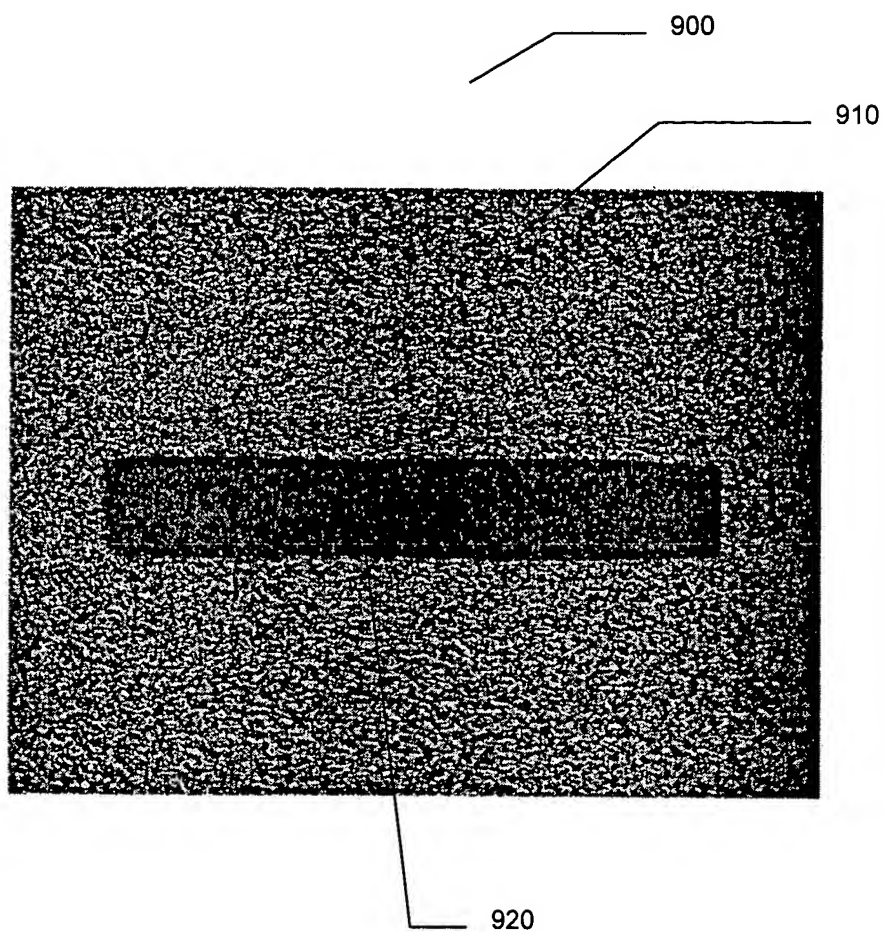


FIGURE 9

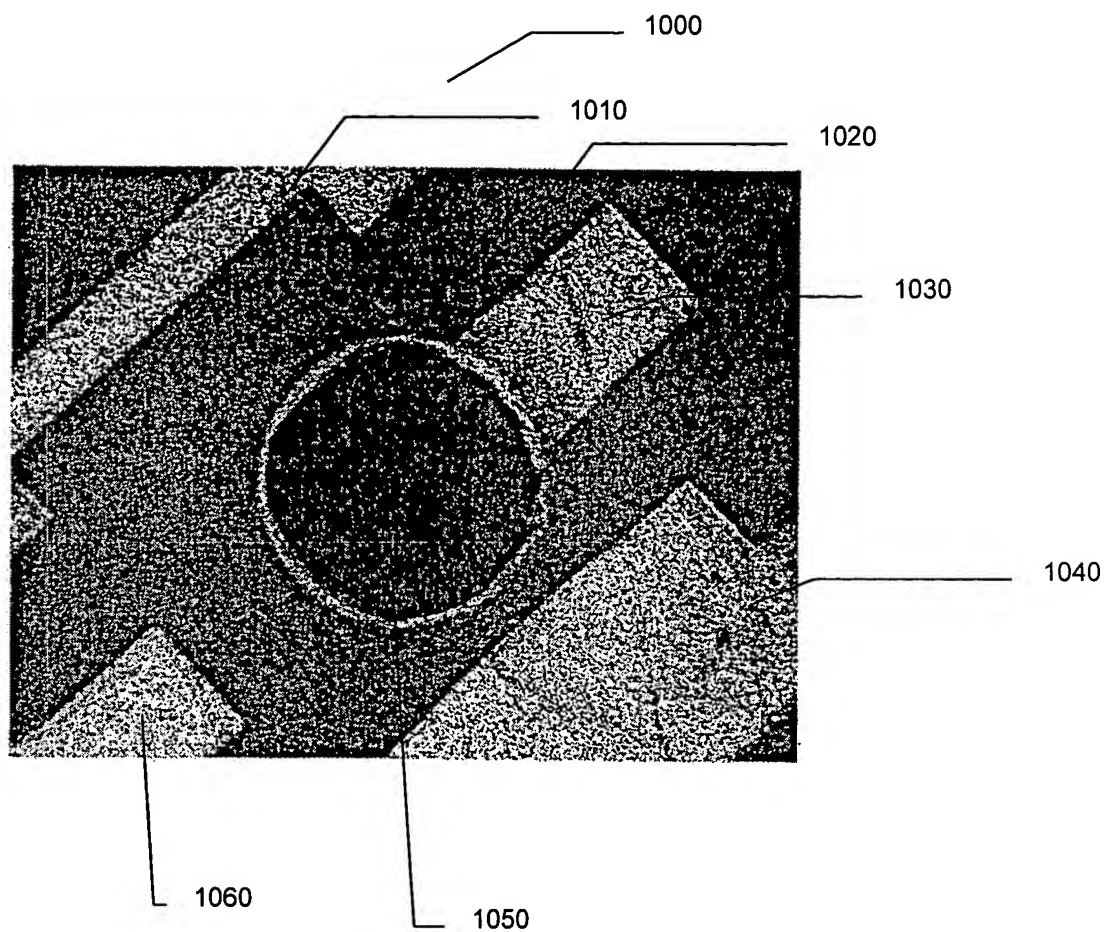


FIGURE 10

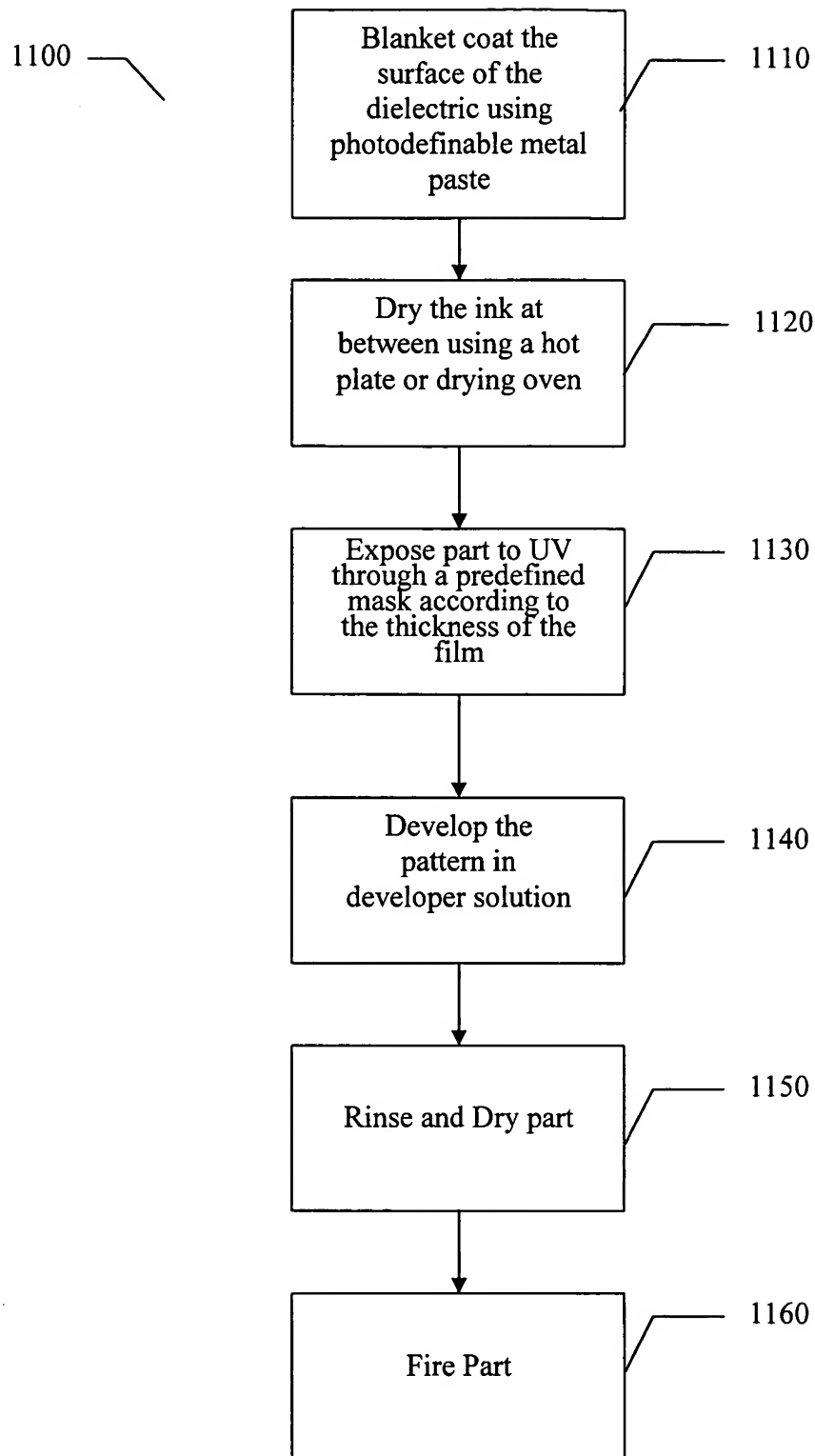


FIGURE 11

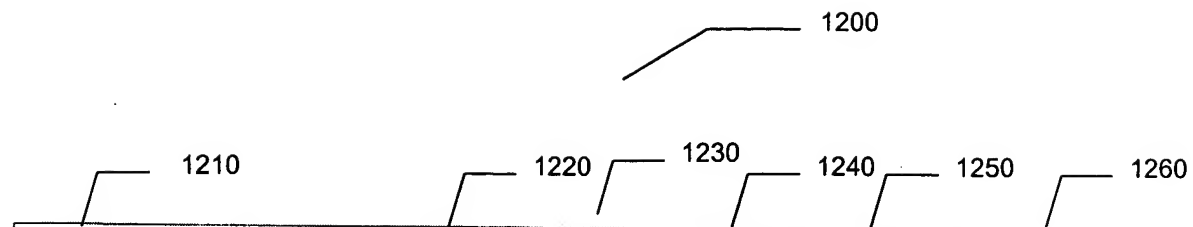


Diagram illustrating a process flow 1200, which branches into several steps: 1210, 1220, 1230, 1240, 1250, and 1260. The process flow is represented by a line that starts at 1200 and branches out to each of these steps.

| Process Steps | Photo-Define | Screen-Print | Etching | Typical Semi-conductor patterning | Laser Patterning |
|---|--------------|---------------------------|---------|-----------------------------------|----------------------------|
| Apply wet metal | Yes | Yes | Yes | No | Yes |
| Drying of metal/photoresist | Yes | Yes | Yes | Yes | Yes |
| Exposing of metal or photoresist | Yes | No | Yes | Yes | No |
| Developing of metal or photoresist | Yes | Yes | Yes | Yes | No |
| Firing of Metal | Yes | Yes | Yes | No | Yes |
| Further trimming to obtain correct dimensions (not RF trimming) | No | Yes limited in dimensions | No | No | Limited to laser spot size |
| Vacuum Metallization (limited in deposition thicknesses) | No | No | No | Yes | No |
| Chemical Etching | No | No | Yes | Yes | No |
| Post Annealing/Cleaning | No | Yes | Yes | Yes | Yes |

FIGURE 12